

Particle in Cell simulations of RF and DC break down

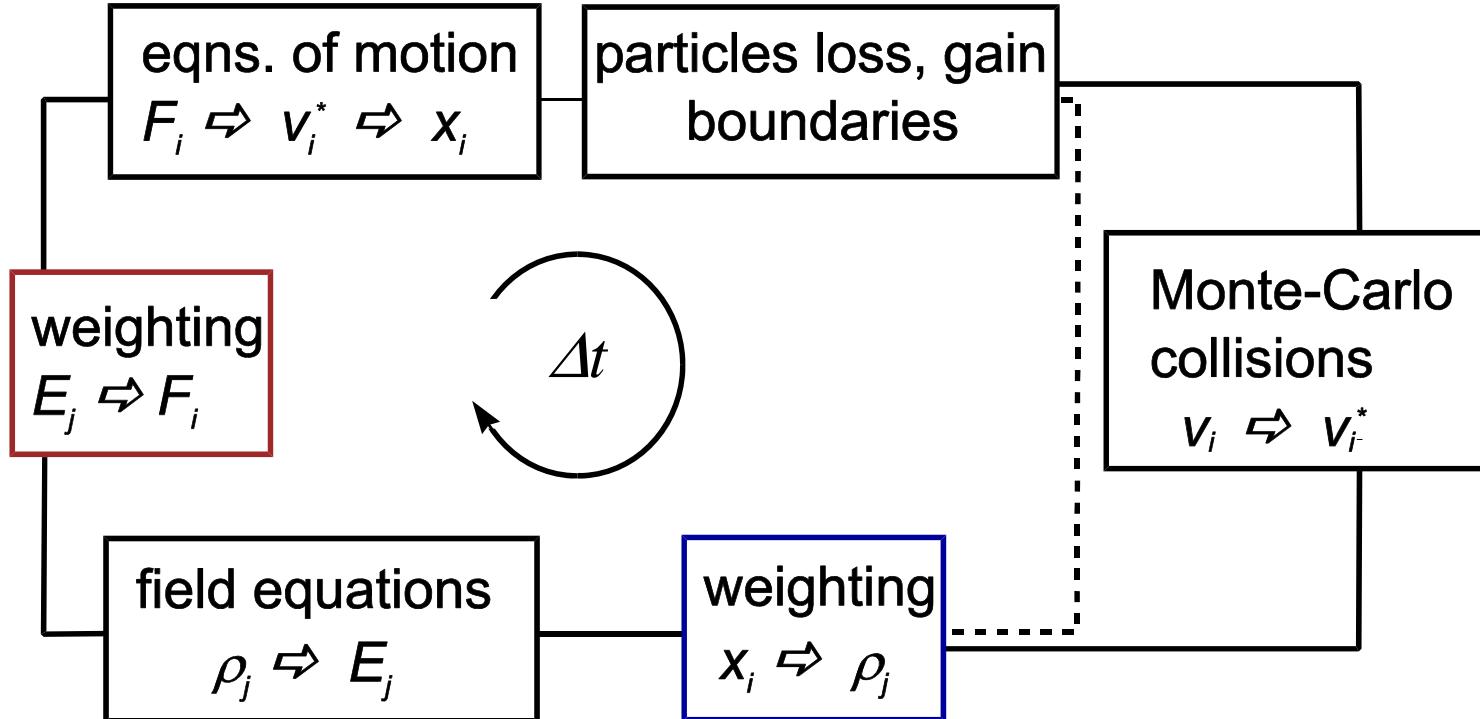
Konstantin Matyash, Ralf Schneider

HGF-Junior research group “COMAS”:

Study of effects on materials in contact with plasma, either with fusion or low-temperature plasmas;

Development of computational multi-scale tools

Particle in Cell model

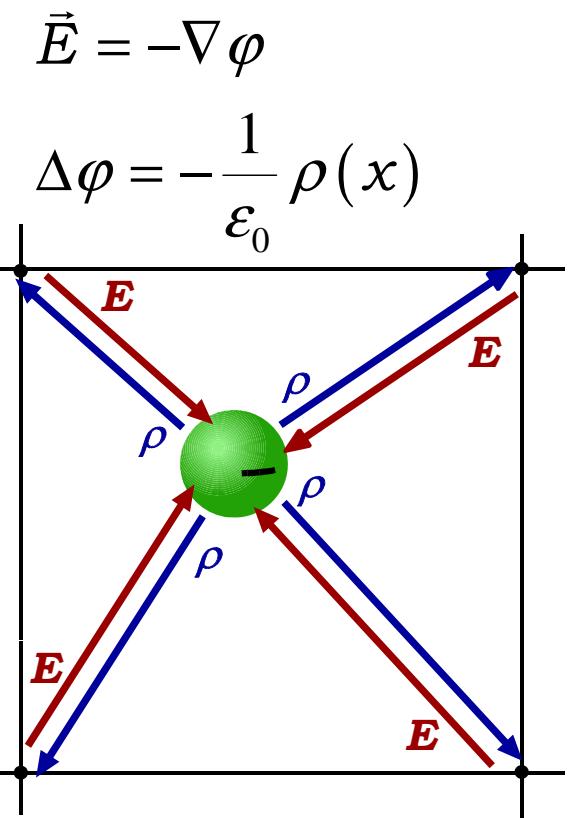


$$\rho = \sum_i \frac{q_i}{\Delta x \Delta y} S(x - x_i)$$

$$S(x) = \begin{cases} \left(1 - \frac{|x|}{\Delta x}\right) \left(1 - \frac{|y|}{\Delta y}\right) & |x| \leq \Delta x \quad \text{and} \quad |y| \leq \Delta y \\ 0 & \text{otherwise} \end{cases}$$

$$\frac{d\vec{x}}{dt} = \vec{v}$$

$$\frac{d\vec{v}}{dt} = \frac{q}{m} (\vec{E} + \vec{v} \times \vec{B})$$

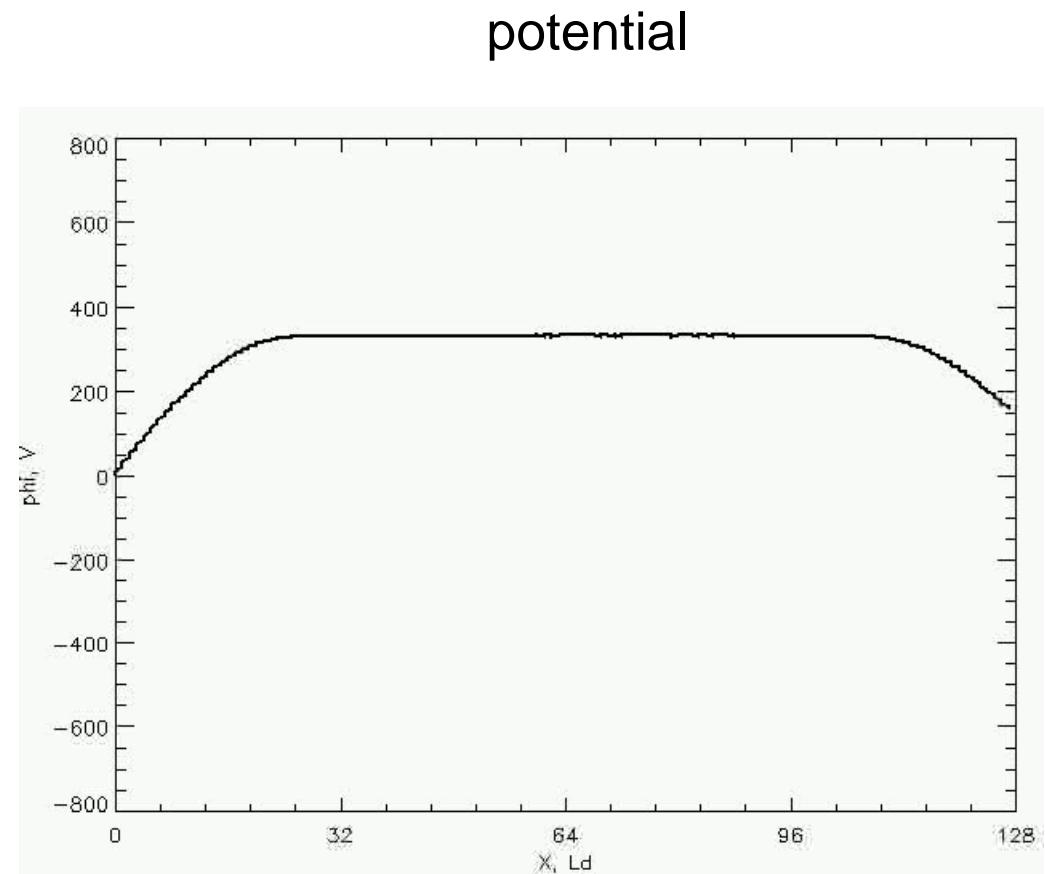


PIC simulation: RF capacitive discharge

Parallel plate RF discharge

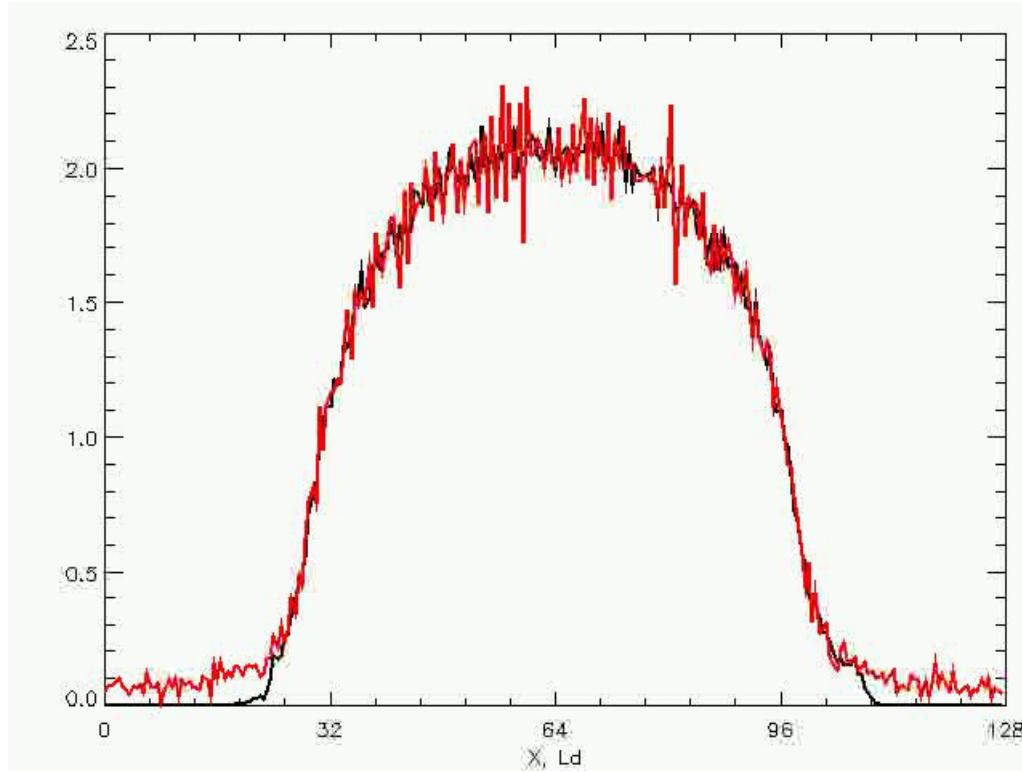
$f_{RF} = 13.56$ MHz , RF peak-to-peak voltage $\sim 200 - 1600$ V

Gas : Oxygen, pressure $p = 1 - 100$ Pa, electron density $n_e \sim 10^9 - 10^{10}$ cm $^{-3}$

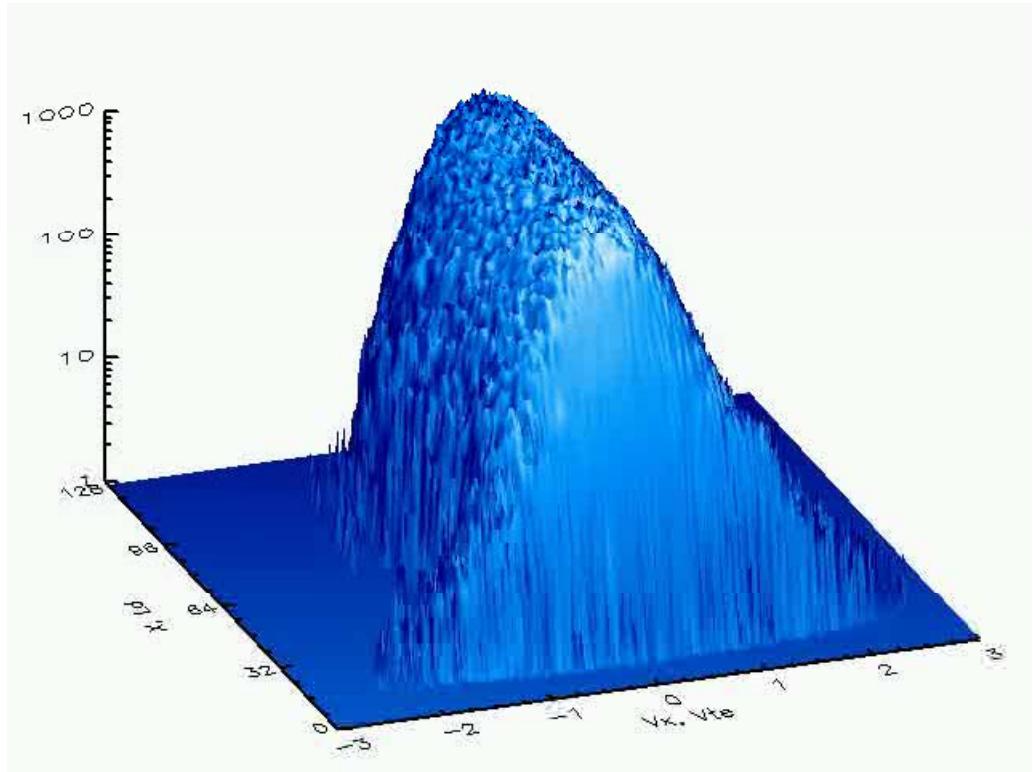


PIC simulation: RF capacitive discharge

Electron and O_2^+ density, 10^9 cm^{-3}

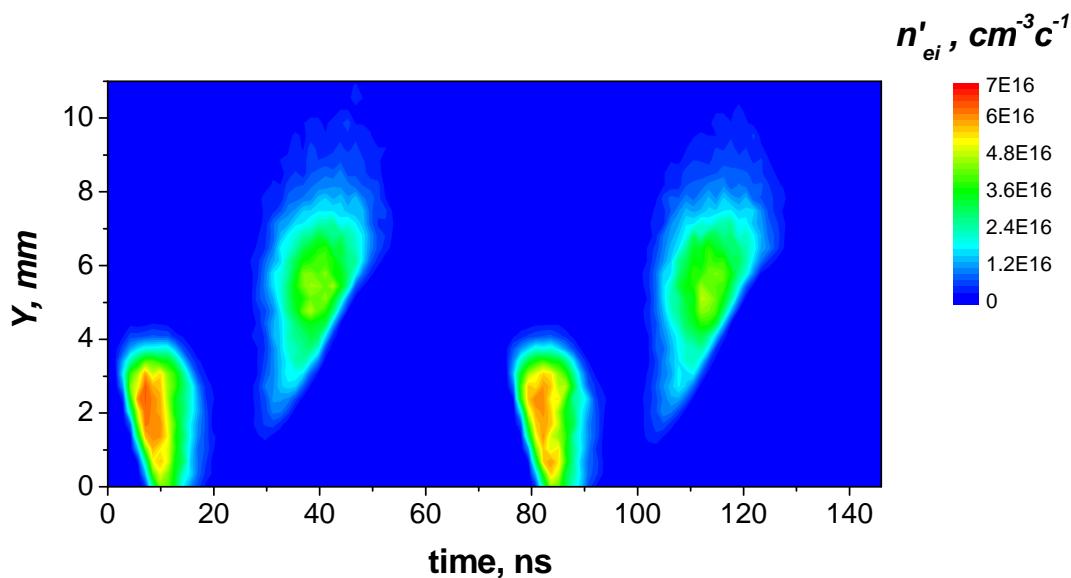


electron parallel velocity distribution
10 Pa, 250 V

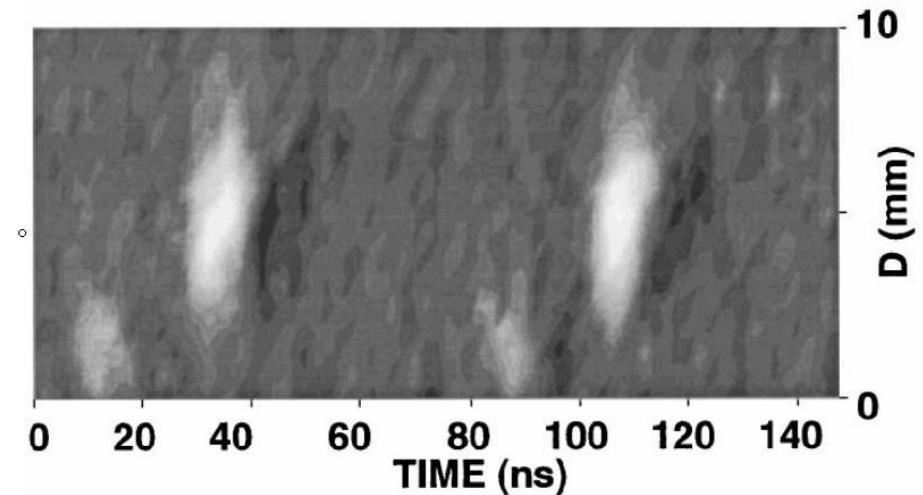


PIC simulation: RF capacitive discharge

electron-impact ionization rate
simulation



653.3 nm excitation rate
experiment

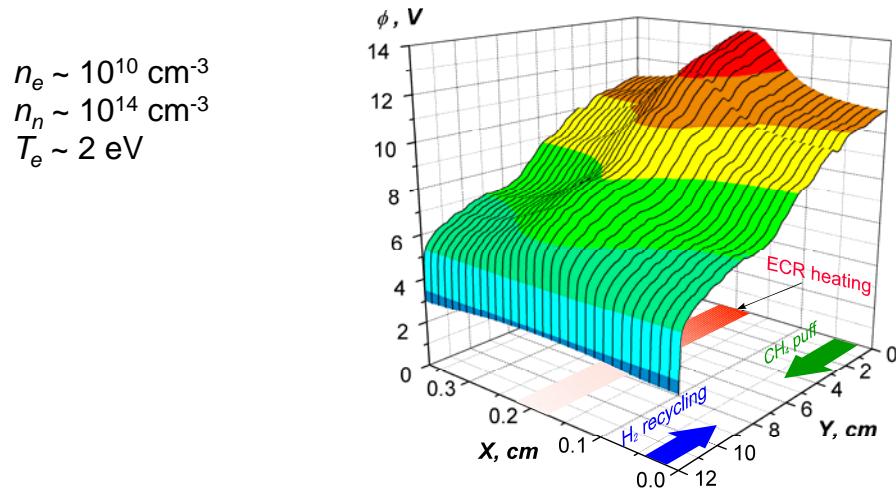


C.M.O. Mahony et al.,
Appl. Phys. Lett. **71** (1997) 608.

double peak structure due to sheath reversal

Particle-in-Cell code applications

ECR plasma



Parasitic plasma under AUG divertor

Plasma detected below roof baffle of Div IIb

Typical parameters:

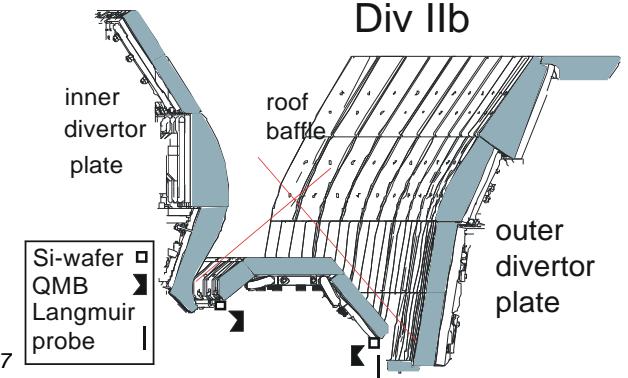
$$4 \cdot 10^8 < n_e < 7 \cdot 10^{11} \text{ cm}^{-3}$$

$$5 < T_e < 15 \text{ eV}$$

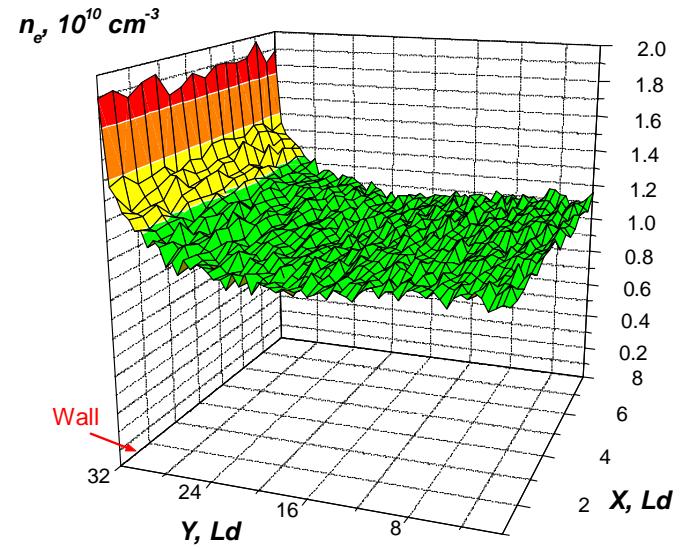
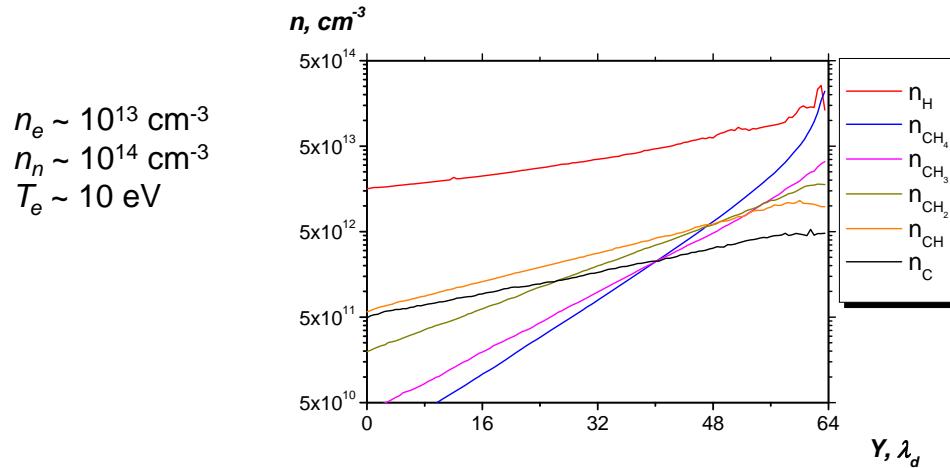
Scaling: $n_e \sim$

$$\text{Radiation}^{2.7} \cdot \text{Particles_flux}^{0.7}$$

Plasma originated by photoionisation or photoeffect!

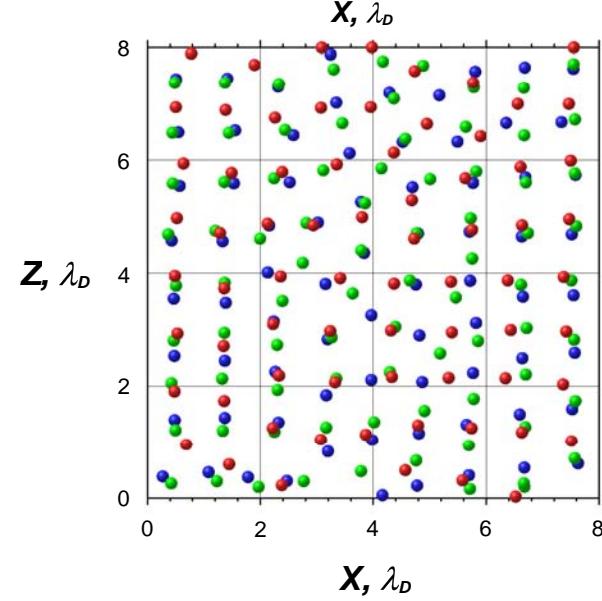
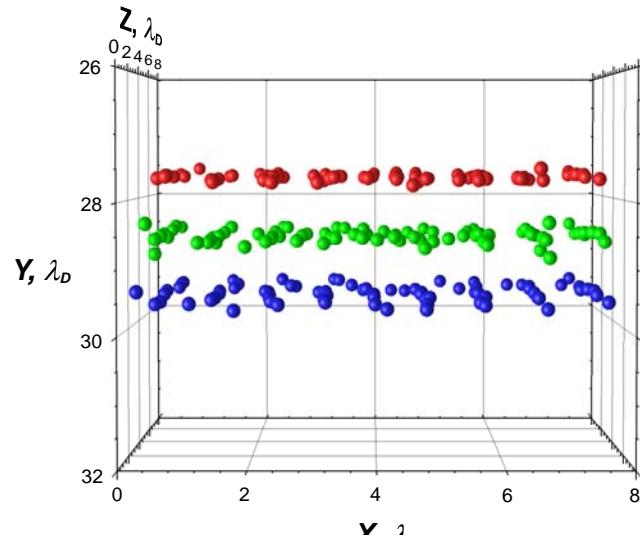


Recycling in SOL

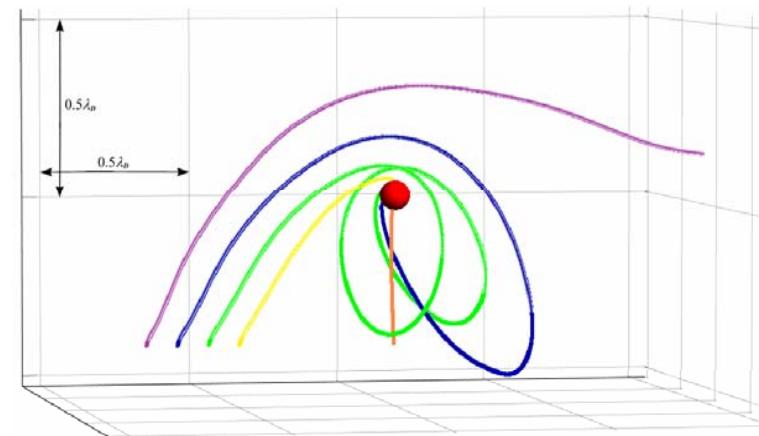


Particle-in-Cell code applications

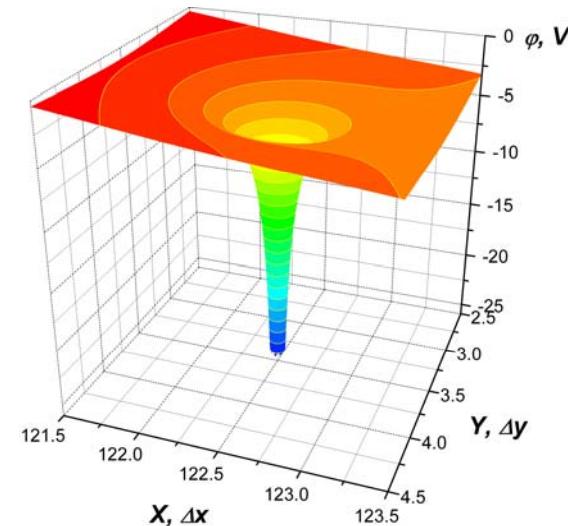
Dusty plasmas and plasma crystals



Ion trajectories close to the dust grain



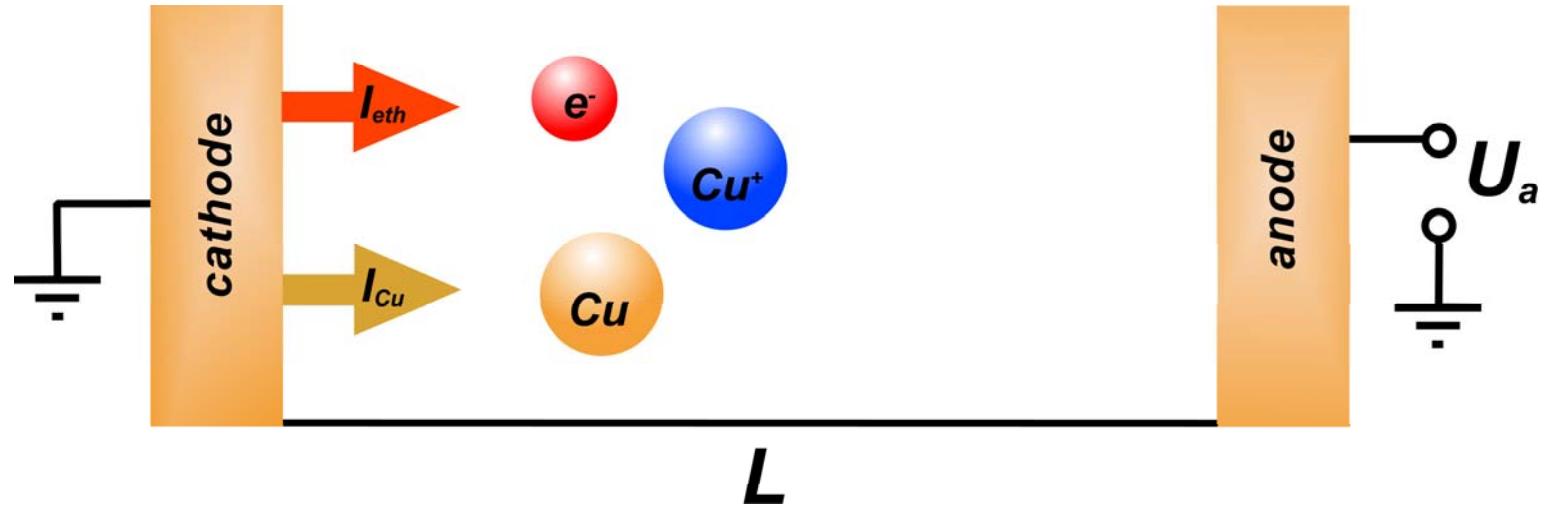
Potential close the dust grain



PIC modeling of arcing: DC discharge

$L = 20 \mu\text{m}$

$U_a = +10 \text{ kV}$



Species included: e^- , Cu^+ , Cu

- electrodes material is Copper.
- the constant electron thermo-emission current $I_{eth} = 2.35 \times 10^6 \text{ A/cm}^2$ from the cathode is assumed.
- the constant flux of evaporated copper atoms from the cathode $I_{Cu} = 0.1I_{eth}/e$ is assumed

Simplistic surface interaction model:

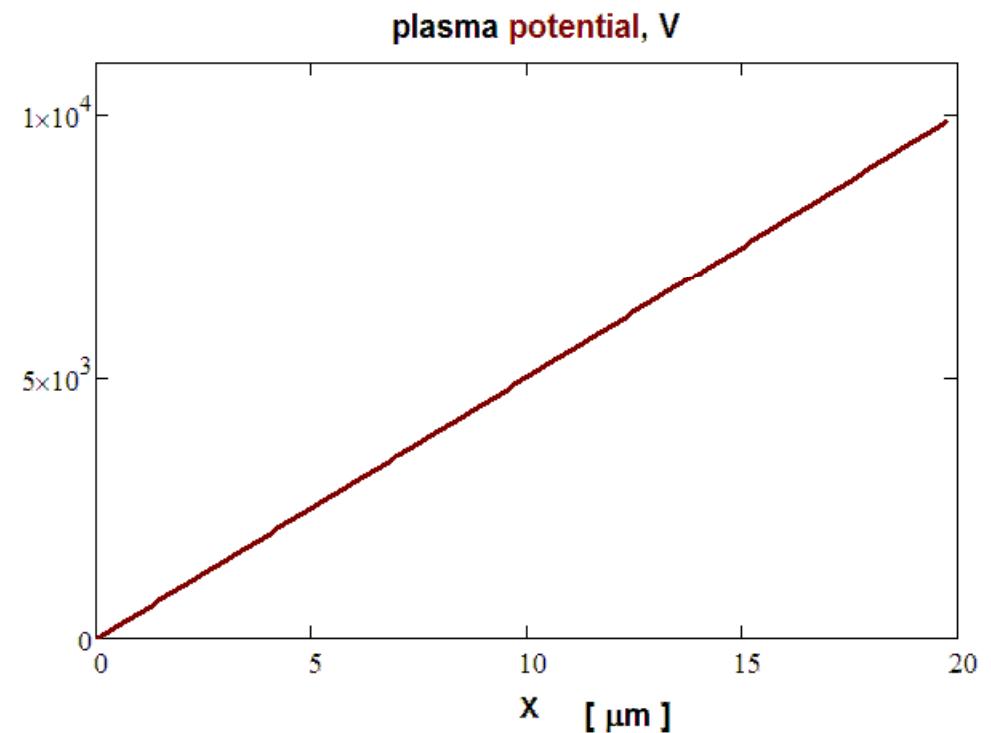
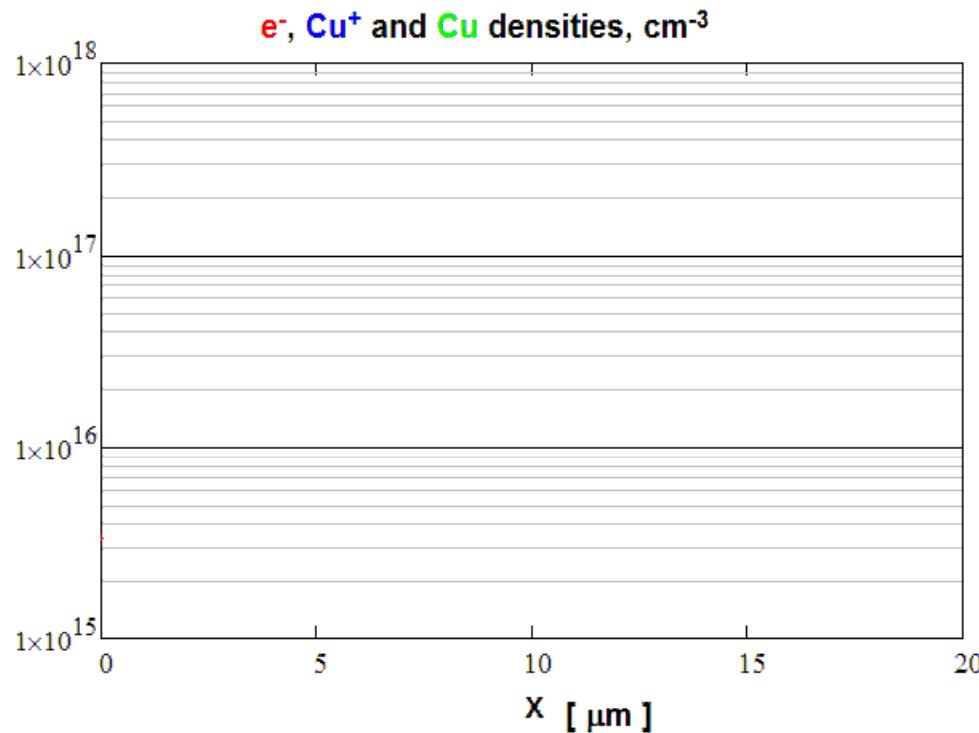
- each Cu^+ ion hitting electrode surface sputters the Cu atom with probability 100%
- each electron hitting the electrode surface sputters the Cu atom with probability 1%.
- each Cu atom hitting surface is reflected back

Collisions:

- Coulomb collisions for the (e^-, e^-) , (Cu^+, Cu^+) and (e^-, Cu^+)
- | | |
|--------------------------------------|---------------------------------------|
| $e^- + Cu^- \Rightarrow e^- + Cu^-$ | electron - neutral elastic collision |
| $e^- + Cu^+ \Rightarrow 2e^- + Cu^+$ | electron impact ionization |
| $Cu^+ + Cu \Rightarrow Cu^+ + Cu$ | charge exchange and momentum transfer |
| $Cu^- + Cu \Rightarrow Cu + Cu$ | elastic collisions |

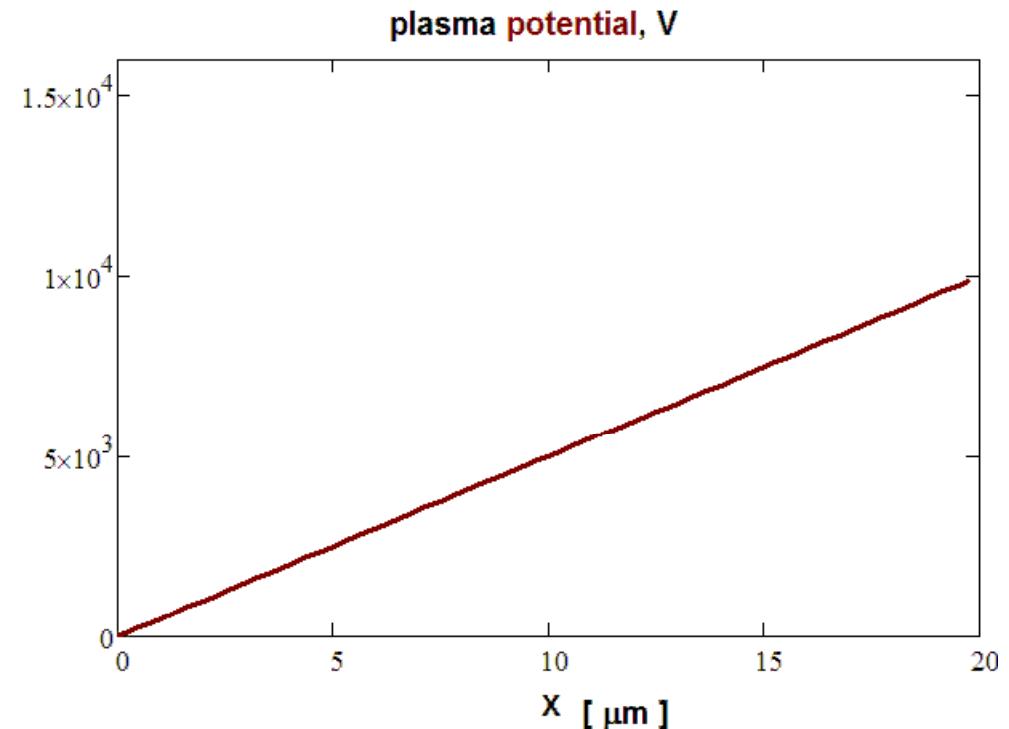
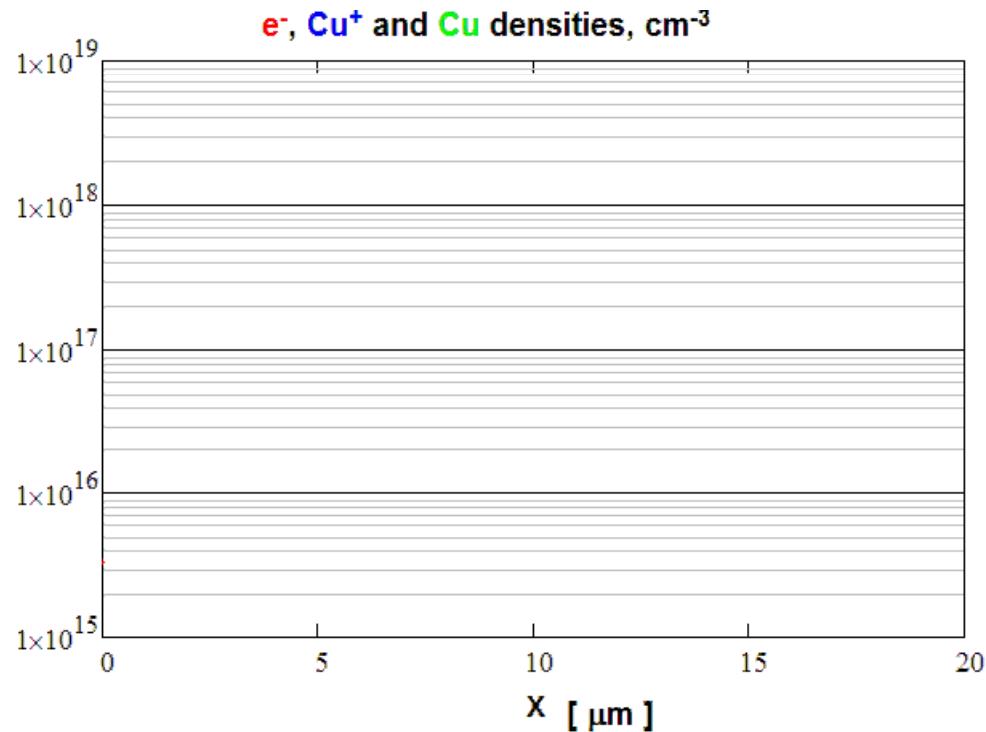
PIC modeling of arcing: DC discharge

Start-up phase of the discharge (the first 0.7 ns)



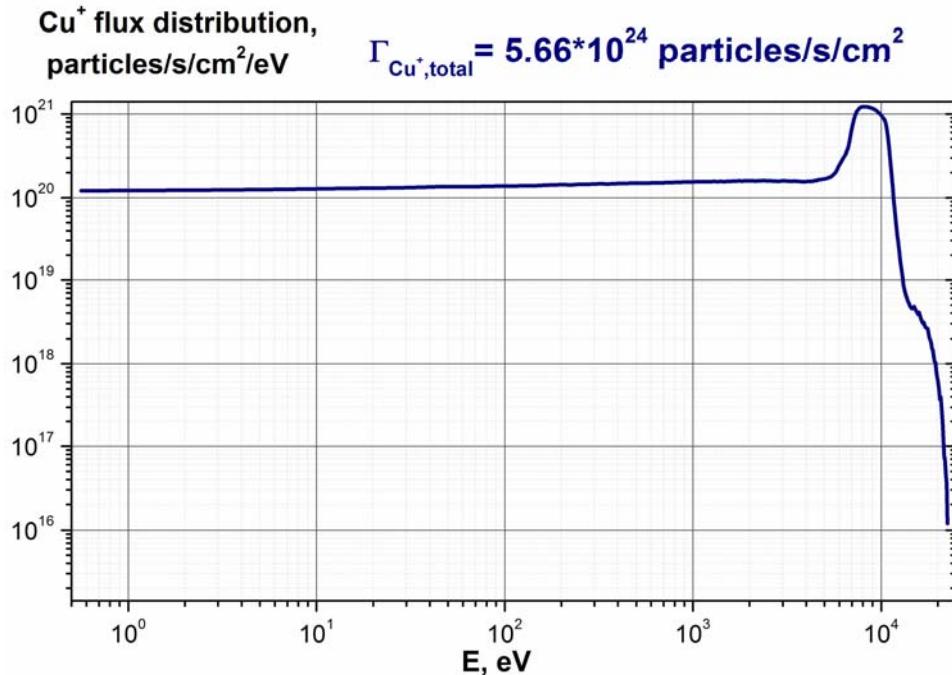
PIC modeling of arcing: DC discharge

Simulated time 18 ns

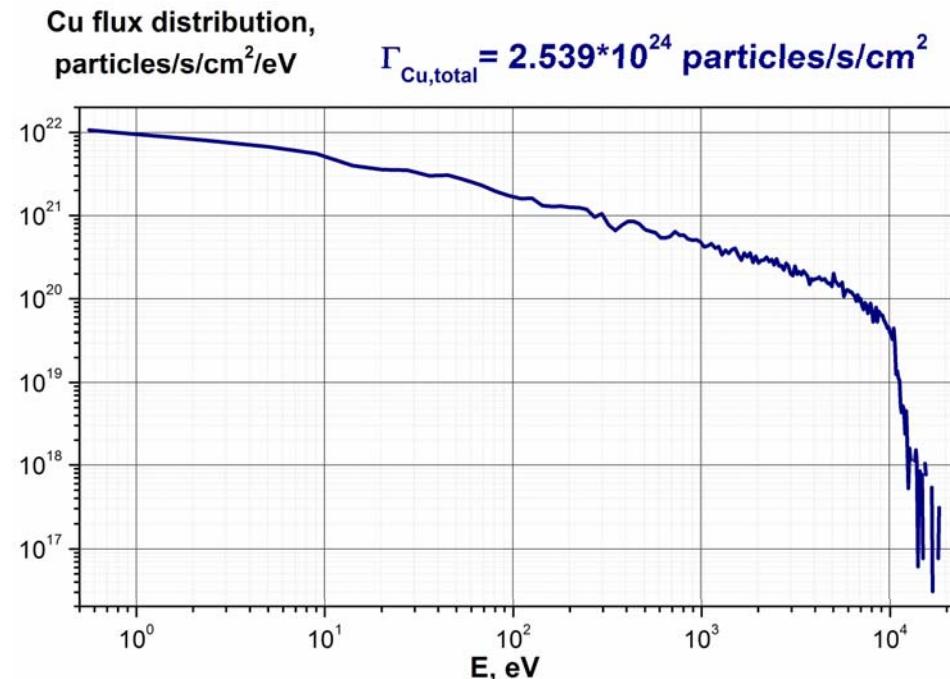


PIC modeling of arcing: DC discharge

Cu⁺ flux energy composition at the cathode



Cu flux energy composition at the cathode

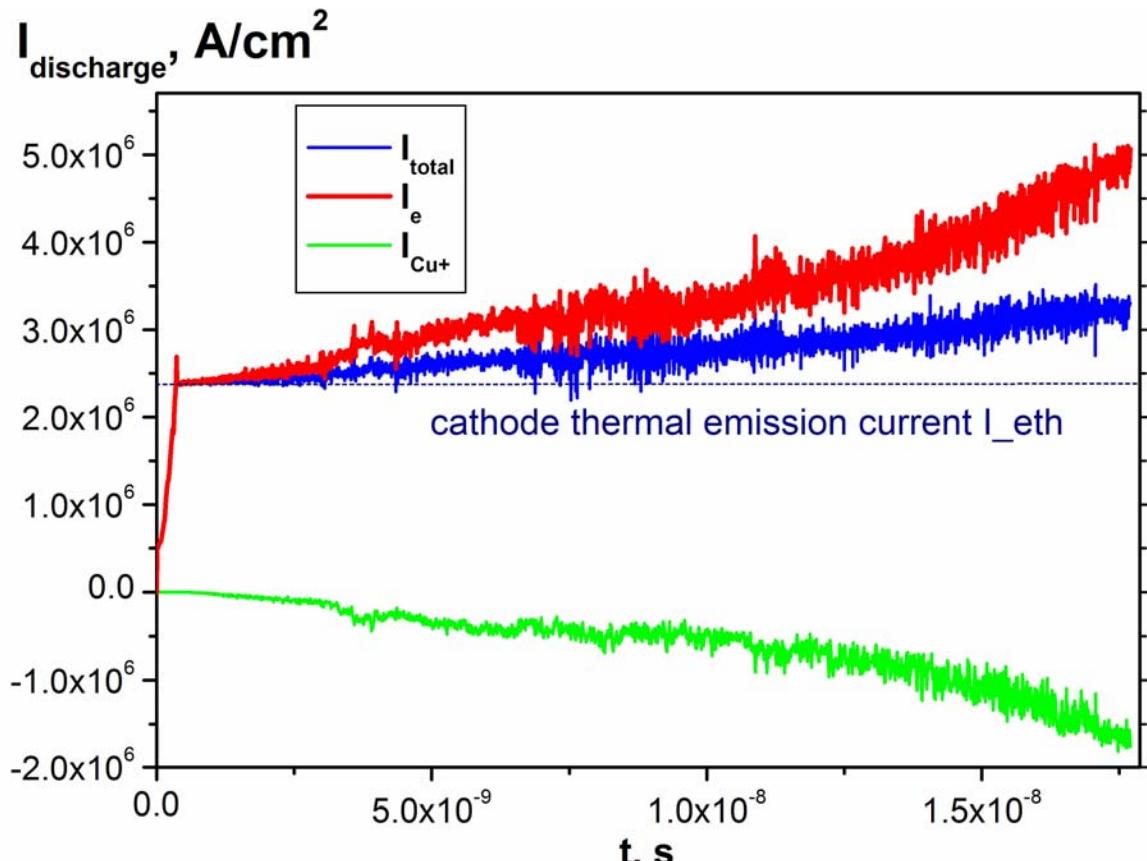


Maximum energy corresponds to sheath potential drop
Lower energy part is populated by collisions with neutrals

High energy neutrals due to charge exchange

PIC modeling of arcing: DC discharge

Discharge current to anode



Main results:

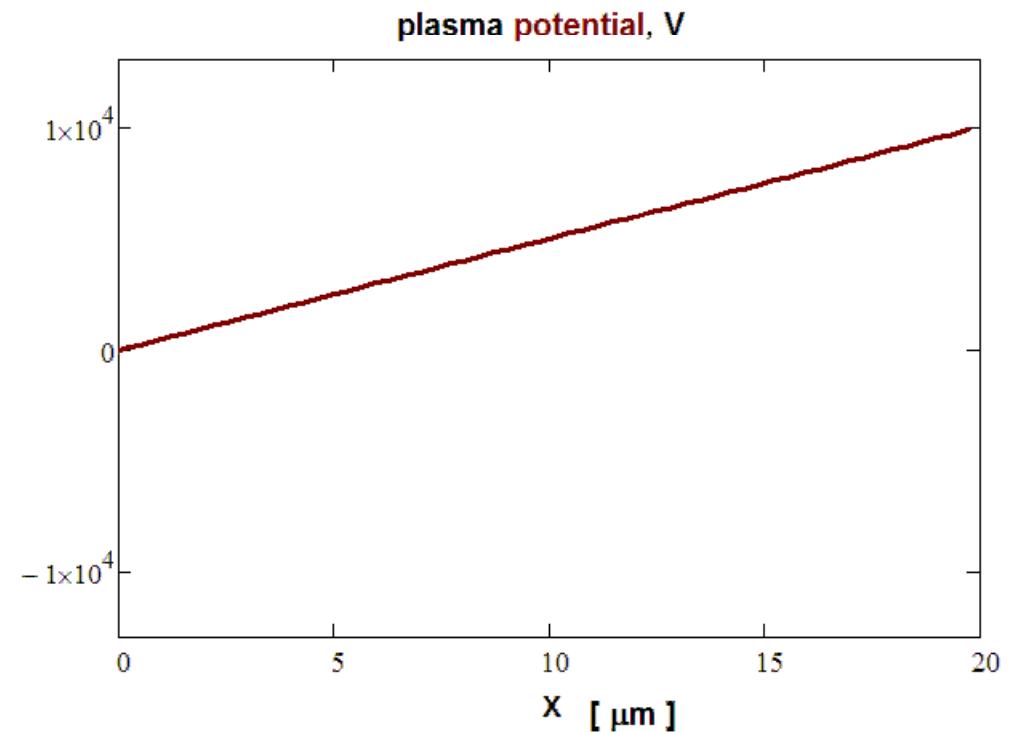
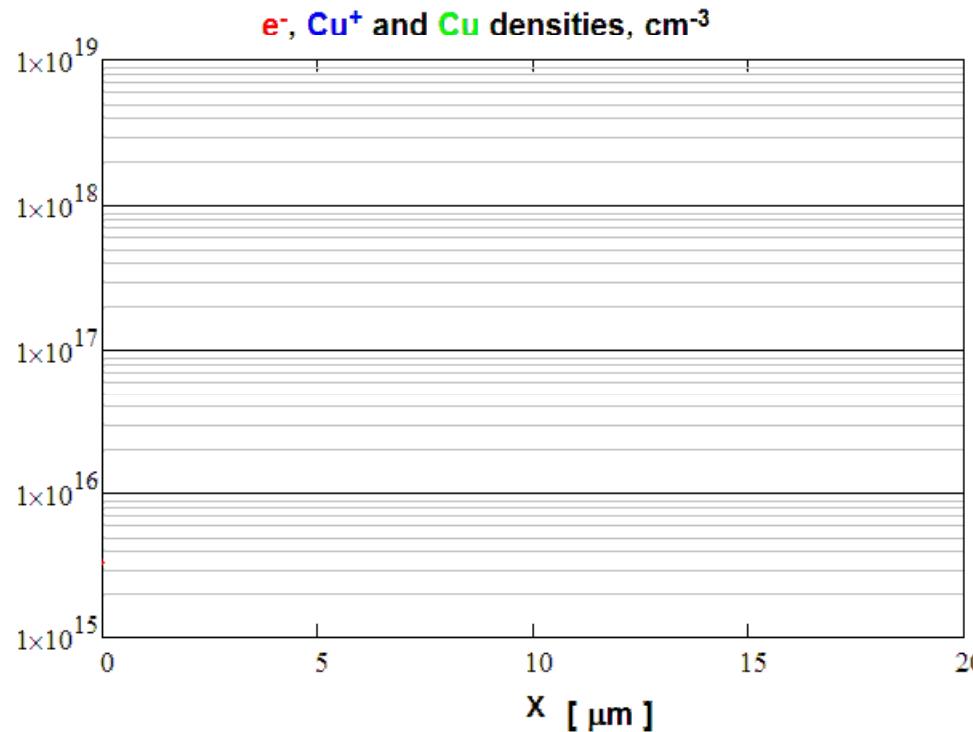
- **Cu** atoms evaporated from cathode are ionized by the electrons accelerated in the gap, creating e^- , Cu^+ plasma
- The flux of the plasma particles to the electrodes enhances the sputtering, increasing the concentration of the **Cu** atoms in the gap
- The plasma space charge start to influence the external electric field in the gap when the Debye length becomes smaller than the electrode spacing.
- Electric field is concentrated in sheath $\sim 8\lambda_{De}$

$$\lambda_{De} = \sqrt{\frac{\epsilon_0 k T_e}{n_e e^2}}$$

PIC modeling of arcing: RF discharge

Same geometry and the model as for DC case,
only now right electrode is powered with RF voltage $U_{RF} = 10 \text{ kV}, f_{RF} = 11.75 \text{ GHz}$

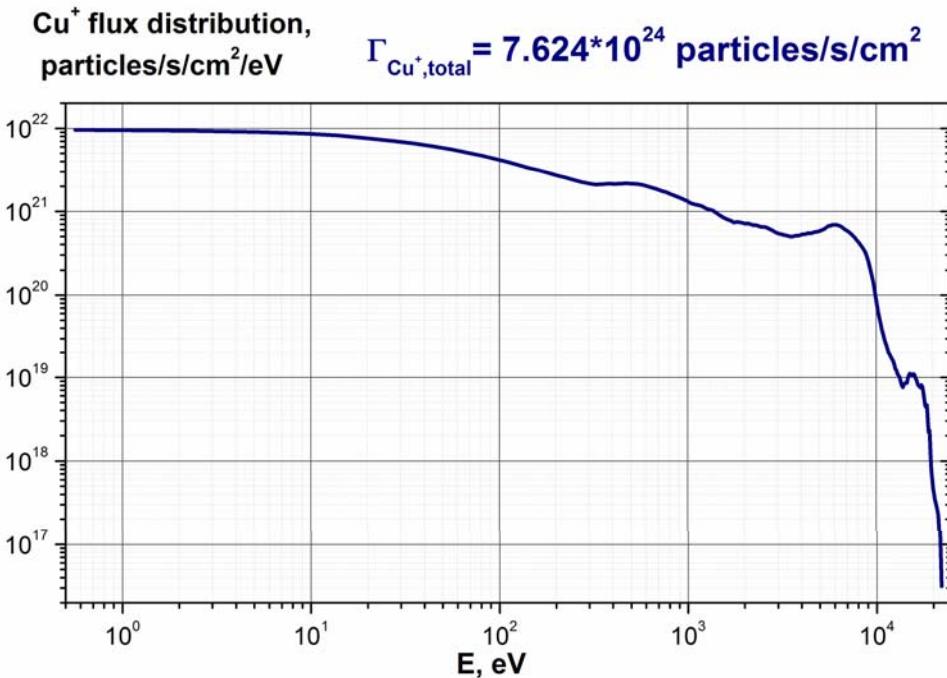
Simulated time $\sim 18 \text{ ns}$



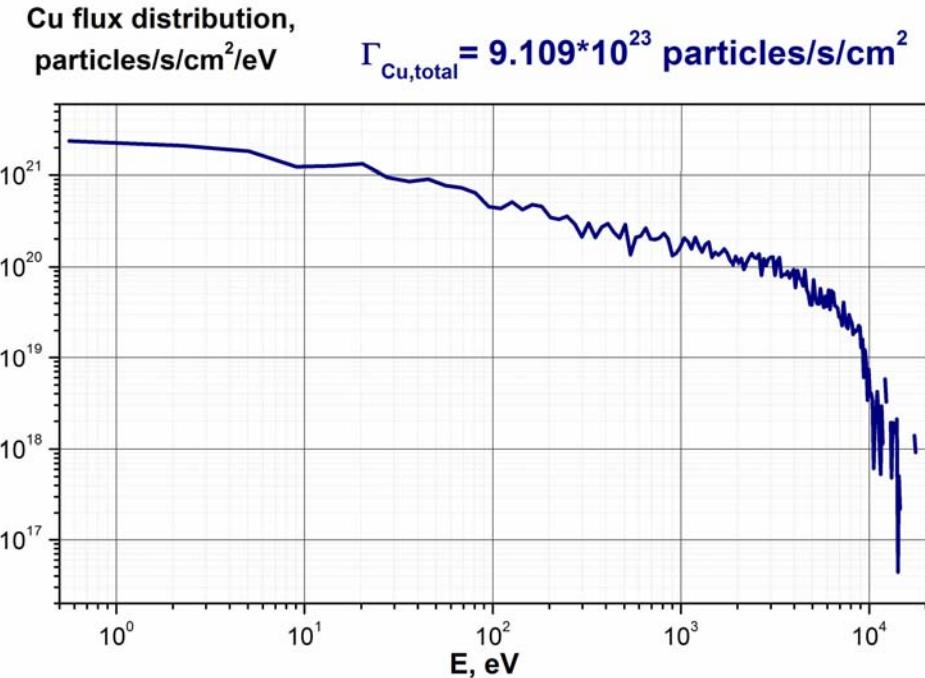
Here frames are taken at $13/12T_{RF}$, so one can see RF dynamics

PIC modeling of arcing: RF discharge

Cu⁺ flux energy composition at the powered electrode

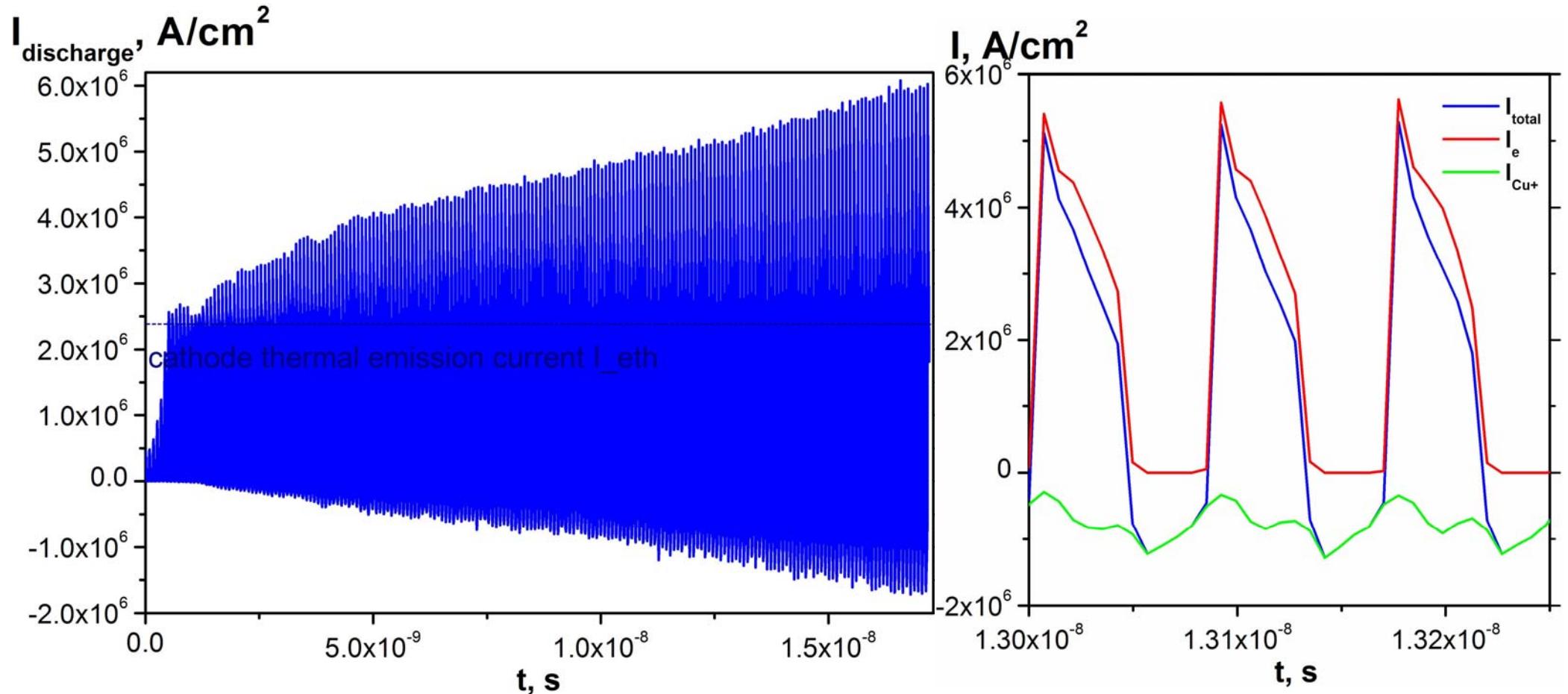


Cu flux energy composition at the powered electrode



PIC modeling of arcing: RF discharge

Discharge current to powered electrode



more results at <http://www.ipplmpg.de/~knm/CERN/spark2.html>

Towards the integrated modeling of arcing

Particle-in-Cell modeling of arcing

- electric field concentrated in sheath
- triggered by electron field emission
- fluxes of plasma particles increase emission from the electrodes

Integrated Particle-in-Cell and Molecular Dynamics modeling of arcing

- energetic particles create surface damage
- explains experimentally observed cluster emission
- scaling studies on the way
- CERN PhD student position for Helga Timko (starting next year)

Thank you!